

# BGA3018

1 GHz 18 dB gain wideband amplifier MMIC

Rev. 3 — 26 September 2013

Product data sheet

## 1. Product profile

### 1.1 General description

The BGA3018 MMIC is a wideband amplifier with internal biasing. It is designed specifically for high linearity CATV line extenders and drop amplifiers over a frequency range of 5 MHz to 1006 MHz. The LNA is housed in a lead free 3-pin SOT89 package.

### 1.2 Features and benefits

- Internally biased
- Flat gain
- High linearity with an IP<sub>3O</sub> of 40 dBm and an IP<sub>2O</sub> of 60 dBm
- Noise figure of 2.1 dB
- 75 Ω input and output impedance
- Operating from 5 V to 8 V supply

### 1.3 Applications

- General wideband amplifiers.
- CATV return amplifier; frequency ranges of 5 MHz to 300 MHz.
- CATV infrastructure network driver in optical nodes (FTTx), distribution amplifiers, trunk amplifiers and line extenders in the frequency range from 40 MHz to 1006 MHz.
- The product is ideally suited for applications as drop amplifiers in CATV distribution systems such as FTTH

### 1.4 Quick reference data

**Table 1. Quick reference data**

Bandwidth 40 MHz to 1006 MHz;  $T_{amb} = 25\text{ °C}$ ; typical values at  $V_{CC} = 8\text{ V}$ ;  $Z_S = Z_L = 75\text{ }\Omega$ ;  $R1 = 470\text{ }\Omega$ ;  $R2 = 300\text{ }\Omega$ .

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{CC}$	supply voltage	RF input AC coupled	7.6	8	8.4	V
$I_{CC(tot)}$	total supply current		-	120	135	mA
$T_{amb}$	ambient temperature		-40	-	+85	°C
NF	noise figure	$f = 500\text{ MHz}$	-	2.1	2.6	dB
$P_{L(1dB)}$	output power at 1 dB gain compression		23.5	25	-	dBm
IP <sub>3O</sub>	output third-order intercept point		[1] 36	40	-	dBm
IP <sub>2O</sub>	output second-order intercept point		[2] -	60	-	dBm

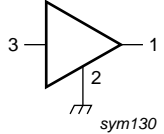
[1] The fundamental frequencies ( $f_1$ ) and ( $f_2$ ) lay between 40 MHz and 1006 MHz. The intermodulation product (IM3) is  $2 \times f_2 - f_1$ , where  $f_2 = f_1 \pm 6\text{ MHz}$ . Input power  $P_i = -20\text{ dBm}$ .

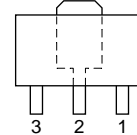
[2] The fundamental frequencies ( $f_1$ ) and ( $f_2$ ) lay between 40 MHz and 1006 MHz. The intermodulation product (IM2) is  $|f_2 - f_1|$ , with  $40\text{ MHz} < |f_1 - f_2| < 1006\text{ MHz}$ . Input power  $P_i = -20\text{ dBm}$ .



## 2. Pinning information

**Table 2. Pinning**

Pin	Description	Simplified outline	Graphic symbol
1	RF_OUT and biasing	[1]	
2	GND	[2]	
3	RF_IN	[1]	



[1] This pin is DC-coupled and requires an external DC-blocking capacitor.

[2] The center metal base of the SOT89 also functions as heatsink for the power amplifier.

## 3. Ordering information

**Table 3. Ordering information**

Type number	Package		Version
	Name	Description	
BGA3018	-	plastic surface-mounted package; exposed die pad for good heat transfer; 3 leads	SOT89
OM7860	EVB	1 GHz 18 dB gain wideband amplifier application	-
OM7864	EVB	5 MHz to 300 MHz 18 dB reverse amplifier application	-
OM7868	EVB	40 MHz to 1006 MHz push-pull amplifier application	-
OM7861	EVB	BGA301x wideband variable gain amplifier application	-

## 4. Marking

**Table 4. Marking codes**

Type number	Marking code	Description
BGA3018	*6Y	* = W : made in China

## 5. Limiting values

**Table 5. Limiting values**

*In accordance with the Absolute Maximum Rating System (IEC 60134).*

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{CC}$	supply voltage	RF input AC coupled	-0.6	+15	V
$P_i$	input power	single tone	-	20	dBm
$T_{stg}$	storage temperature		-65	+150	°C
$T_j$	junction temperature		-	150	°C
$T_{amb}$	ambient temperature		-40	+85	°C
$V_{ESD}$	electrostatic discharge voltage	Human Body Model (HBM); According JEDEC standard 22-A114E	2	-	kV
		Charged Device Model (CDM); According JEDEC standard 22-C101B	2	-	kV

## 6. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions	Typ	Unit
$R_{th(j-sp)}$	thermal resistance from junction to solder point		40	K/W

## 7. Characteristics

### 7.1 Forward application

Table 7. Characteristics at  $V_{CC} = 8\text{ V}$

Bandwidth 40 MHz to 1006 MHz;  $T_{amb} = 25\text{ }^{\circ}\text{C}$ ; typical values at  $V_{CC} = 8\text{ V}$ ;  $Z_S = Z_L = 75\text{ }\Omega$ ;  $R1 = 470\text{ }\Omega$ ;  $R2 = 300\text{ }\Omega$ .

Symbol	Parameter	Conditions	Min	Typ	Max	Unit	
$V_{CC}$	supply voltage	RF input AC coupled	7.6	8	8.4	V	
$I_{CC(tot)}$	total supply current		-	120	135	mA	
$ S_{21} ^2$	insertion power gain		17	18	19	dB	
$SL_{sl}$	slope straight line		-	0.5	-	dB	
FL	flatness of frequency response		-	0.5	-	dB	
NF	noise figure	f = 50 MHz	-	1.9	2.4	dB	
		f = 500 MHz	-	2.1	2.6	dB	
		f = 1000 MHz	-	2.5	3.0	dB	
$RL_{in}$	input return loss	f = 50 MHz	-	18.5	-	dB	
		f = 500 MHz	-	20	-	dB	
		f = 1000 MHz	-	28	-	dB	
$RL_{out}$	output return loss	f = 50 MHz	-	24	-	dB	
		f = 500 MHz	-	28	-	dB	
		f = 1000 MHz	-	16	-	dB	
$P_{L(1dB)}$	output power at 1 dB gain compression		23.5	25	-	dBm	
IP3 <sub>O</sub>	output third-order intercept point		[1]	36	40	-	dBm
IP2 <sub>O</sub>	output second-order intercept point		[2]	-	60	-	dBm
CTB	composite triple beat		[3]	-	-75	-	dBc
CSO	composite second-order distortion		[3]	-	-60	-	dBc

[1] The fundamental frequencies ( $f_1$ ) and ( $f_2$ ) lay between 40 MHz and 1006 MHz. The intermodulation product (IM3) is  $2 \times f_2 - f_1$ , where  $f_2 = f_1 \pm 6\text{ MHz}$ . Input power  $P_i = -20\text{ dBm}$ .

[2] The fundamental frequencies ( $f_1$ ) and ( $f_2$ ) lay between 40 MHz and 1006 MHz. The intermodulation product (IM2) is  $|f_2 - f_1|$ , with  $40\text{ MHz} < |f_1 - f_2| < 1006\text{ MHz}$ . Input power  $P_i = -20\text{ dBm}$ .

[3] Measured with 132 NTSC channels  $V_O = 30\text{ dBmV}$ .

**Table 8. Characteristics at  $V_{CC} = 5\text{ V}$** 

Bandwidth 40 MHz to 1006 MHz;  $T_{amb} = 25\text{ }^{\circ}\text{C}$ ; typical values at  $V_{CC} = 5\text{ V}$ ;  $Z_S = Z_L = 75\text{ }\Omega$ ;  $R1 = 470\text{ }\Omega$ ;  $R2 = 300\text{ }\Omega$ .

Symbol	Parameter	Conditions	Min	Typ	Max	Unit	
$V_{CC}$	supply voltage	RF input AC coupled	4.75	5	5.25	V	
$I_{CC(\text{tot})}$	total supply current		-	75	85	mA	
$ S_{21} ^2$	insertion power gain		-	18	-	dB	
$SL_{sl}$	slope straight line		-	0.5	-	dB	
FL	flatness of frequency response		-	0.5	-	dB	
NF	noise figure	f = 50 MHz	-	1.9	-	dB	
		f = 500 MHz	-	2.2	-	dB	
		f = 1000 MHz	-	2.5	-	dB	
$RL_{in}$	input return loss	f = 50 MHz	-	18.5	-	dB	
		f = 500 MHz	-	18.5	-	dB	
		f = 1000 MHz	-	28	-	dB	
$RL_{out}$	output return loss	f = 50 MHz	-	26	-	dB	
		f = 500 MHz	-	28	-	dB	
		f = 1000 MHz	-	16	-	dB	
$P_{L(1\text{dB})}$	output power at 1 dB gain compression		-	18	-	dBm	
$IP3_O$	output third-order intercept point		[1]	-	36	-	dBm
$IP2_O$	output second-order intercept point		[2]	-	54	-	dBm
CTB	composite triple beat		[3]	-	-70	-	dBc
CSO	composite second-order distortion		[3]	-	-54	-	dBc

[1] The fundamental frequencies ( $f_1$ ) and ( $f_2$ ) lay between 40 MHz and 1006 MHz. The intermodulation product (IM3) is  $2 \times f_2 - f_1$ , where  $f_2 = f_1 \pm 6\text{ MHz}$ . Input power  $P_i = -20\text{ dBm}$ .

[2] The fundamental frequencies ( $f_1$ ) and ( $f_2$ ) lay between 40 MHz and 1006 MHz. The intermodulation product (IM2) is  $|f_2 - f_1|$ , with  $40\text{ MHz} < |f_1 - f_2| < 1006\text{ MHz}$ . Input power  $P_i = -20\text{ dBm}$ .

[3] Measured with 132 NTSC channels  $V_O = 30\text{ dBmV}$ .

## 7.2 Return application

**Table 9. Characteristics at  $V_{CC} = 8\text{ V}$**

Bandwidth 5 MHz to 300 MHz;  $T_{amb} = 25\text{ }^{\circ}\text{C}$ ; typical values at  $V_{CC} = 8\text{ V}$ ;  $Z_S = Z_L = 75\text{ }\Omega$ ;  $R1 = 470\text{ }\Omega$ ;  $R2 = 300\text{ }\Omega$ .

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{CC}$	supply voltage	RF input AC coupled	7.6	8	8.4	V
$I_{CC(tot)}$	total supply current		-	120	135	mA
$ S_{21} ^2$	insertion power gain		-	18	-	dB
$SL_{sl}$	slope straight line		-	0.5	-	dB
FL	flatness of frequency response		-	0.5	-	dB
NF	noise figure	$f = 50\text{ MHz}$	-	1.9	-	dB
$RL_{in}$	input return loss	$f = 5\text{ MHz}$	-	18.5	-	dB
		$f = 100\text{ MHz}$	-	18.5	-	dB
		$f = 200\text{ MHz}$	-	18.5	-	dB
		$f = 300\text{ MHz}$	-	18.5	-	dB
$RL_{out}$	output return loss	$f = 5\text{ MHz}$	-	18.5	-	dB
		$f = 100\text{ MHz}$	-	18.5	-	dB
		$f = 200\text{ MHz}$	-	18.5	-	dB
		$f = 300\text{ MHz}$	-	18.5	-	dB
$P_{L(1dB)}$	output power at 1 dB gain compression		-	25	-	dBm
$IP3_O$	output third-order intercept point	[1]	-	40	-	dBm
$IP2_O$	output second-order intercept point	[2]	-	60	-	dBm

[1] The fundamental frequencies ( $f_1$ ) and ( $f_2$ ) lay between 5 MHz and 300 MHz. The intermodulation product (IM3) is  $2 \times f_2 - f_1$ , where  $f_2 = f_1 \pm 6\text{ MHz}$ . Input power  $P_i = -20\text{ dBm}$ .

[2] The fundamental frequencies ( $f_1$ ) and ( $f_2$ ) lay between 5 MHz and 300 MHz. The intermodulation product (IM2) is  $|f_2 - f_1|$ , with  $40\text{ MHz} < |f_1 - f_2| < 300\text{ MHz}$ . Input power  $P_i = -20\text{ dBm}$ .

**Table 10. Characteristics at  $V_{CC} = 5\text{ V}$** 

Bandwidth 5 MHz to 300 MHz;  $T_{amb} = 25\text{ °C}$ ; typical values at  $V_{CC} = 5\text{ V}$ ;  $Z_S = Z_L = 75\text{ }\Omega$ ;  
 $R1 = 470\text{ }\Omega$ ;  $R2 = 300\text{ }\Omega$ .

Symbol	Parameter	Conditions	Min	Typ	Max	Unit	
$V_{CC}$	supply voltage	RF input AC coupled	4.75	5	5.25	V	
$I_{CC(tot)}$	total supply current		-	75	85	mA	
$ S_{21} ^2$	insertion power gain		-	18	-	dB	
$SL_{sl}$	slope straight line		-	0.5	-	dB	
FL	flatness of frequency response		-	0.5	-	dB	
NF	noise figure	$f = 50\text{ MHz}$	-	1.9	-	dB	
$RL_{in}$	input return loss	$f = 5\text{ MHz}$	-	18.5	-	dB	
		$f = 100\text{ MHz}$	-	18.5	-	dB	
		$f = 200\text{ MHz}$	-	18.5	-	dB	
		$f = 300\text{ MHz}$	-	18.5	-	dB	
$RL_{out}$	output return loss	$f = 5\text{ MHz}$	-	18.5	-	dB	
		$f = 100\text{ MHz}$	-	18.5	-	dB	
		$f = 200\text{ MHz}$	-	18.5	-	dB	
		$f = 300\text{ MHz}$	-	18.5	-	dB	
$P_{L(1dB)}$	output power at 1 dB gain compression		-	20	-	dBm	
$IP3_O$	output third-order intercept point		[1]	-	36	-	dBm
$IP2_O$	output second-order intercept point		[2]	-	54	-	dBm

[1] The fundamental frequencies ( $f_1$ ) and ( $f_2$ ) lay between 5 MHz and 300 MHz. The intermodulation product (IM3) is  $2 \times f_2 - f_1$ , where  $f_2 = f_1 \pm 6\text{ MHz}$ . Input power  $P_i = -20\text{ dBm}$ .

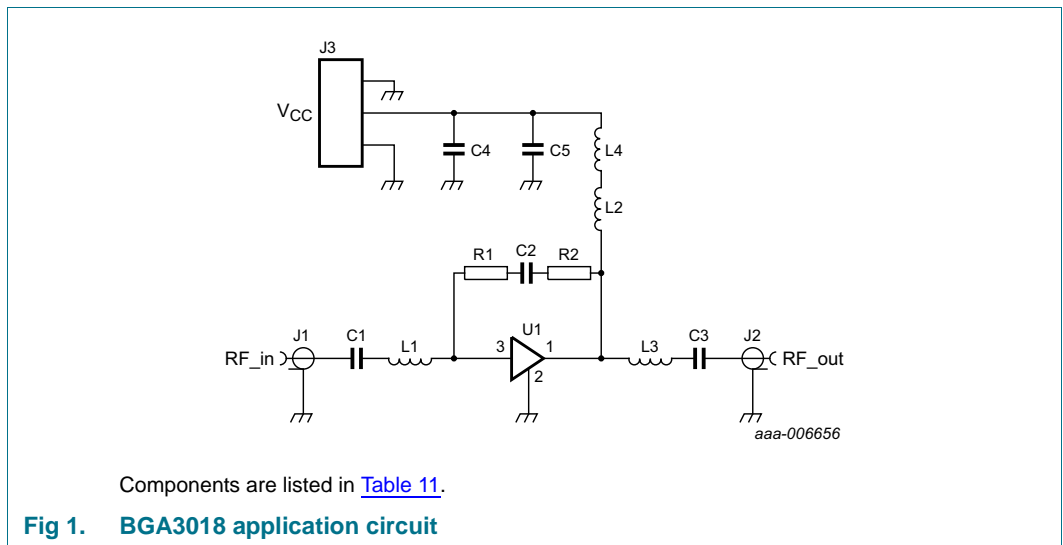
[2] The fundamental frequencies ( $f_1$ ) and ( $f_2$ ) lay between 5 MHz and 300 MHz. The intermodulation product (IM2) is  $|f_2 - f_1|$ , with  $40\text{ MHz} < |f_1 - f_2| < 300\text{ MHz}$ . Input power  $P_i = -20\text{ dBm}$ .

## 8. Application information

### 8.1 Forward application 40 MHz to 1006 MHz

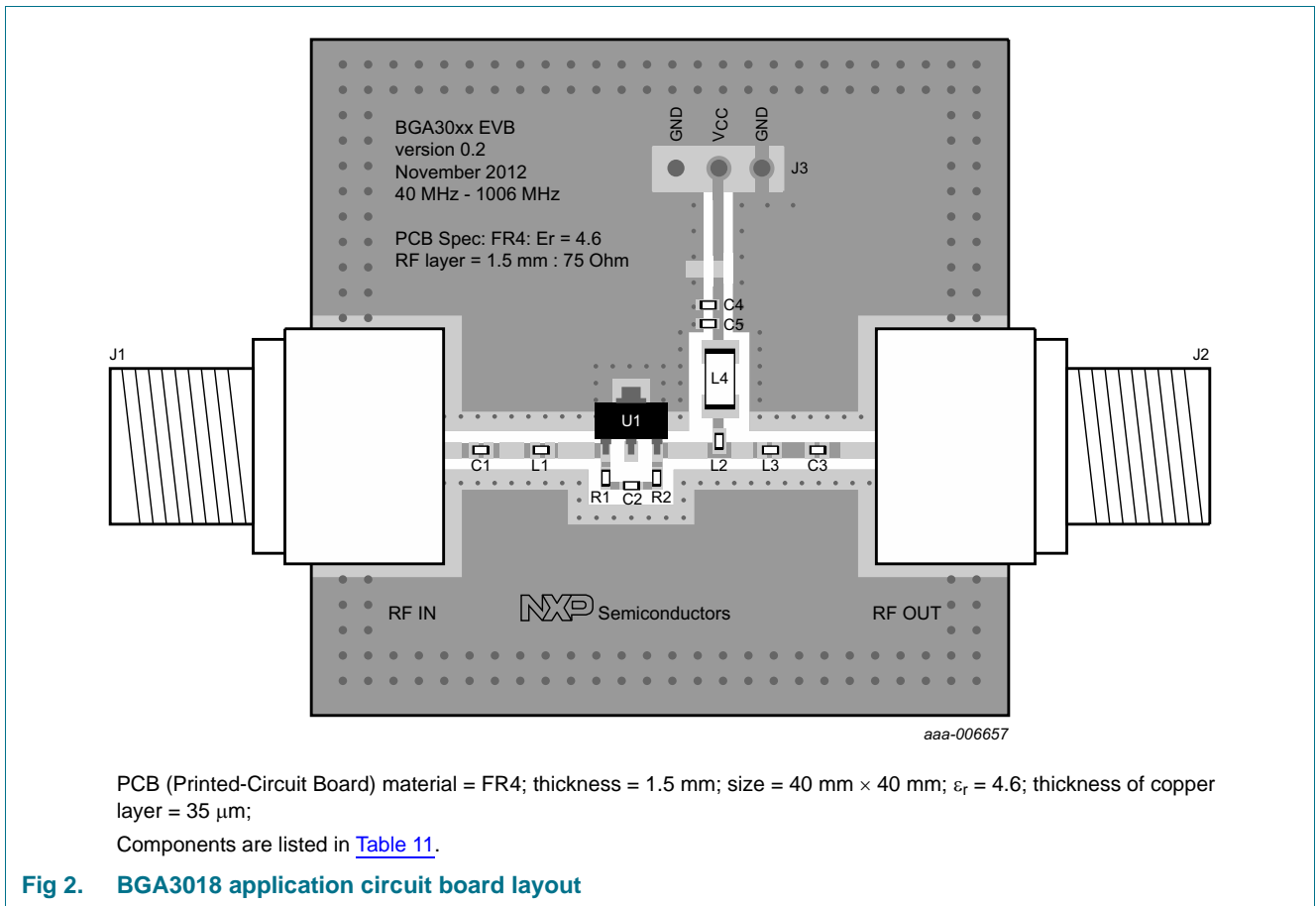
The BGA3018 can be used in other applications. Please contact your local sales representative for more information. Application notes are available on the NXP website.

#### 8.1.1 Forward application circuit



All control and supply lines must be decoupled properly. The decoupling capacitors must be placed as close to the device as possible.

**8.1.2 Forward application circuit board layout**



**Table 11. List of components**

See [Figure 1](#) and [Figure 2](#).

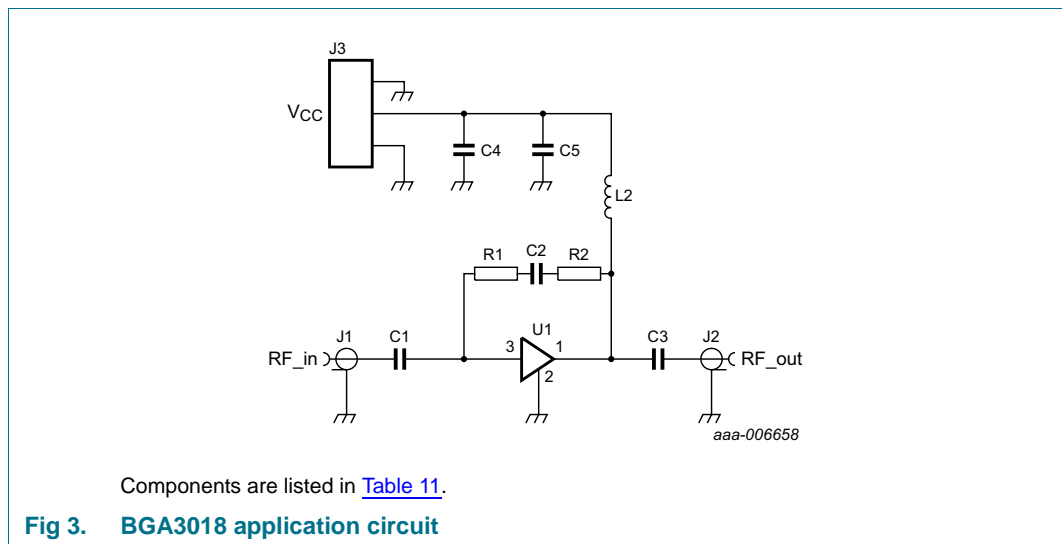
Component	Description	Value	Size	Remarks
C1, C2, C3, C4	capacitor	10 nF	SMD 0402	Murata GRM155R71E103KA01D or capacitor of same quality
C5	capacitor	100 pF	SMD 0402	Murata GRM155C1H101JZ01D or capacitor of same quality
J1, J2	F-connector	75 $\Omega$	-	Bomar 861V509ER6 or F-connector of same quality
J3	header 3-way	-	-	Molex 90121-0763 or header of the same quality
L1, L3	inductor	3.9 nH	SMD 0402	Murata LQG15HS3N9S02D or inductor of same quality
L2	choke	-	SMD 0603	Murata BLM18HD182SN1D or choke of same quality
L4	inductor	880 nH	SMD 1206	Murata LQH31HNR88K03L or inductor of same quality
R1	resistor	470 $\Omega$	SMD 0402	Yageo RC0402FR-07470RL or resistor of same quality
R2	resistor	300 $\Omega$	SMD 0402	Yageo RC0402FR-07300RL or resistor of same quality
U1	BGA3018	-	-	NXP



## 8.2 Return application 5 MHz to 300 MHz

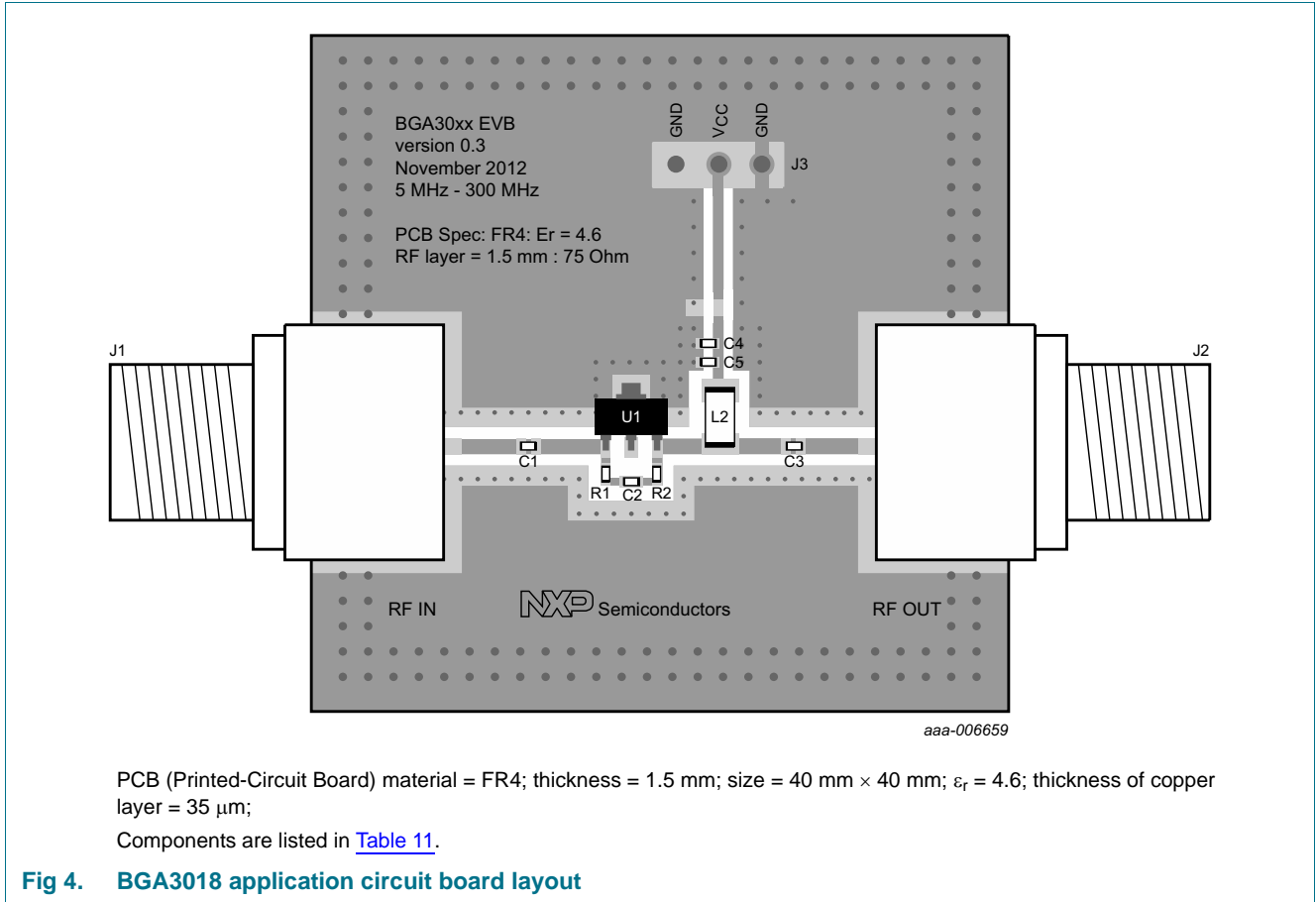
The BGA3018 can be used in other applications. Please contact your local sales representative for more information. Application notes are available on the NXP website.

### 8.2.1 Return application circuit



All control and supply lines must be decoupled properly. The decoupling capacitors must be placed as close to the device as possible.

**8.2.2 Return application circuit board layout**



**Table 12. List of components**

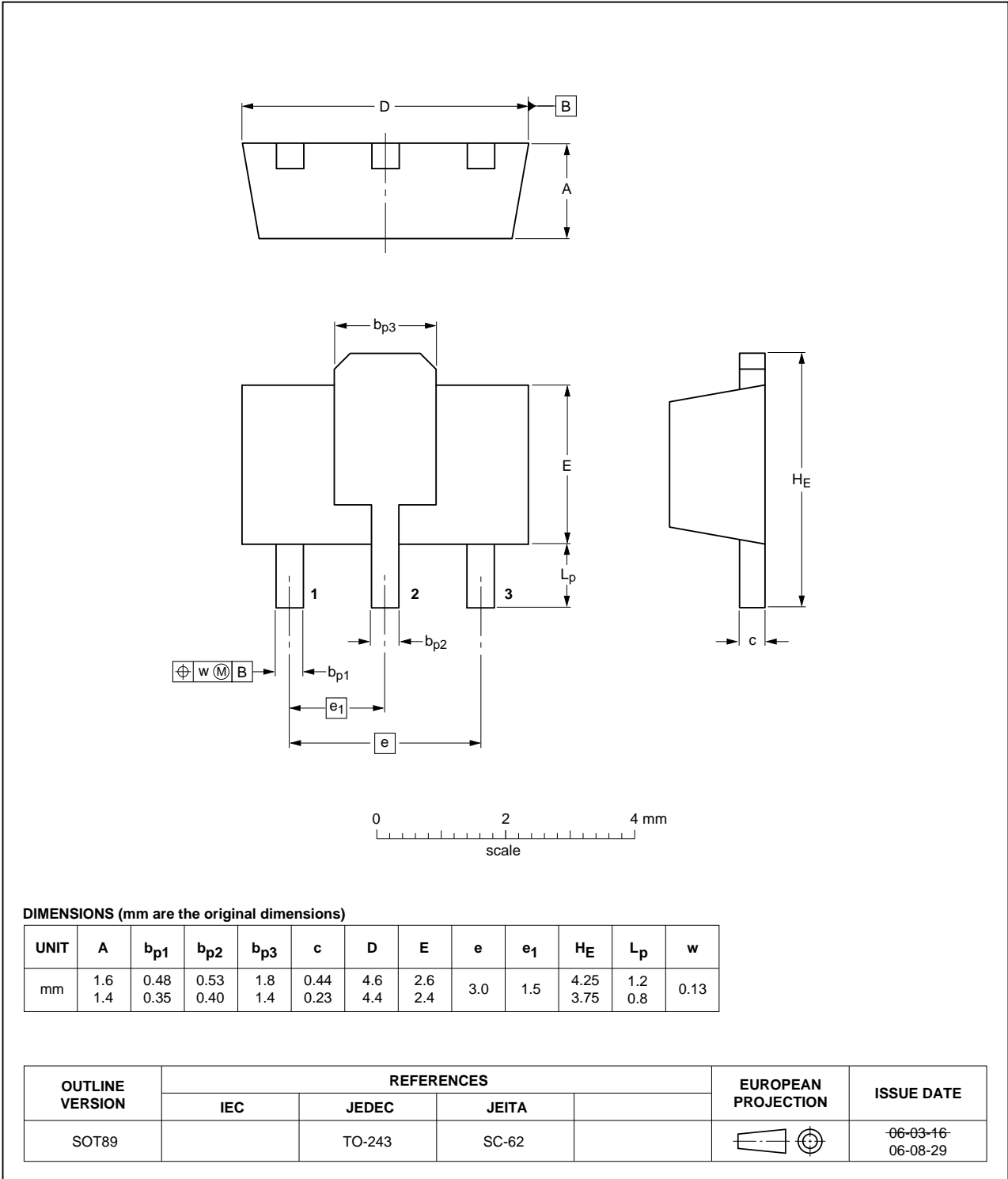
See [Figure 1](#) and [Figure 2](#).

Component	Description	Value	Size	Remarks
C1, C2, C3, C4	capacitor	10 nF	SMD 0402	Murata GRM155R71E103KA01D or capacitor of same quality
C5	capacitor	100 pF	SMD 0402	Murata GRM155C1H101JZ01D or capacitor of same quality
J1, J2	F-connector	75 $\Omega$	-	Bomar 861V509ER6 or F-connector of same quality
J3	header 3-way	-	-	Molex 90121-0763 or header of the same quality
L2	inductor	22 $\mu\text{H}$	SMD 1206	Murata LQH31CN220K03L or inductor of same quality
R1	resistor	470 $\Omega$	SMD 0402	Yageo RC0402FR-07470RL or resistor of same quality
R2	resistor	300 $\Omega$	SMD 0402	Yageo RC0402FR-07300RL or resistor of same quality
U1	BGA3018	-	-	NXP

**9. Package outline**

Plastic surface-mounted package; exposed die pad for good heat transfer; 3 leads

**SOT89**



**Fig 5. Package outline SOT89 (SC-62)**

## 10. Abbreviations

Table 13. Abbreviations

Acronym	Description
CATV	Community Antenna TeleVision
FTTH	Fiber To The Home
FTTx	Fiber To The "x"
LNA	Low-Noise Amplifier
MMIC	Monolithic Microwave Integrated Circuit

## 11. Revision history

Table 14. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
BGA3018 v.3	20130926	Product data sheet	-	BGA3018 v.2
Modifications:	• <a href="#">Table 3 on page 2</a> : Evaluation boards have been added.			
BGA3018 v.2	20130415	Product data sheet	-	BGA3018 v.1
BGA3018 v.1	20130319	Preliminary data sheet	-	-

## 12. Legal information

### 12.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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**14. Contents**

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Please be aware that important notices concerning this document and the product(s) described herein, have been included in section 'Legal information'.